

Status report on μ RWELL-BOT

Kondo Gnanvo, Jefferson Lab

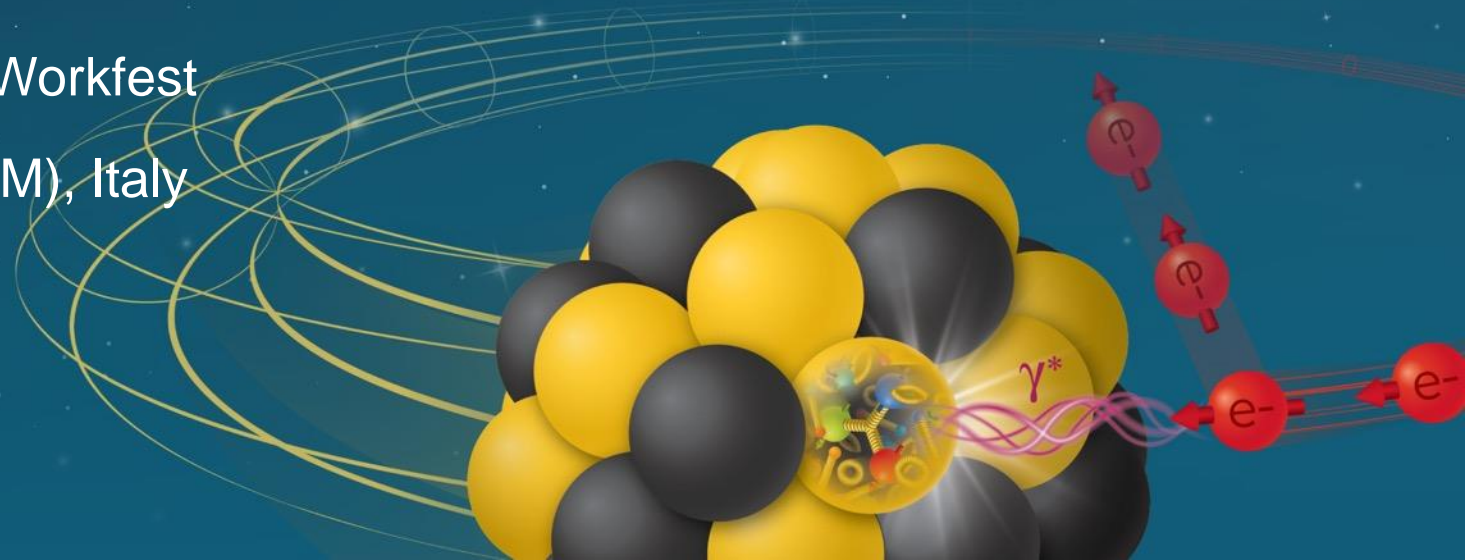
On behalf of the ePIC MPGD DSC

ePIC Collaboration Meeting - MPGD-DSC Workfest

Villa Mondragone, Monte Porzio Catone (RM), Italy

January 24, 2025

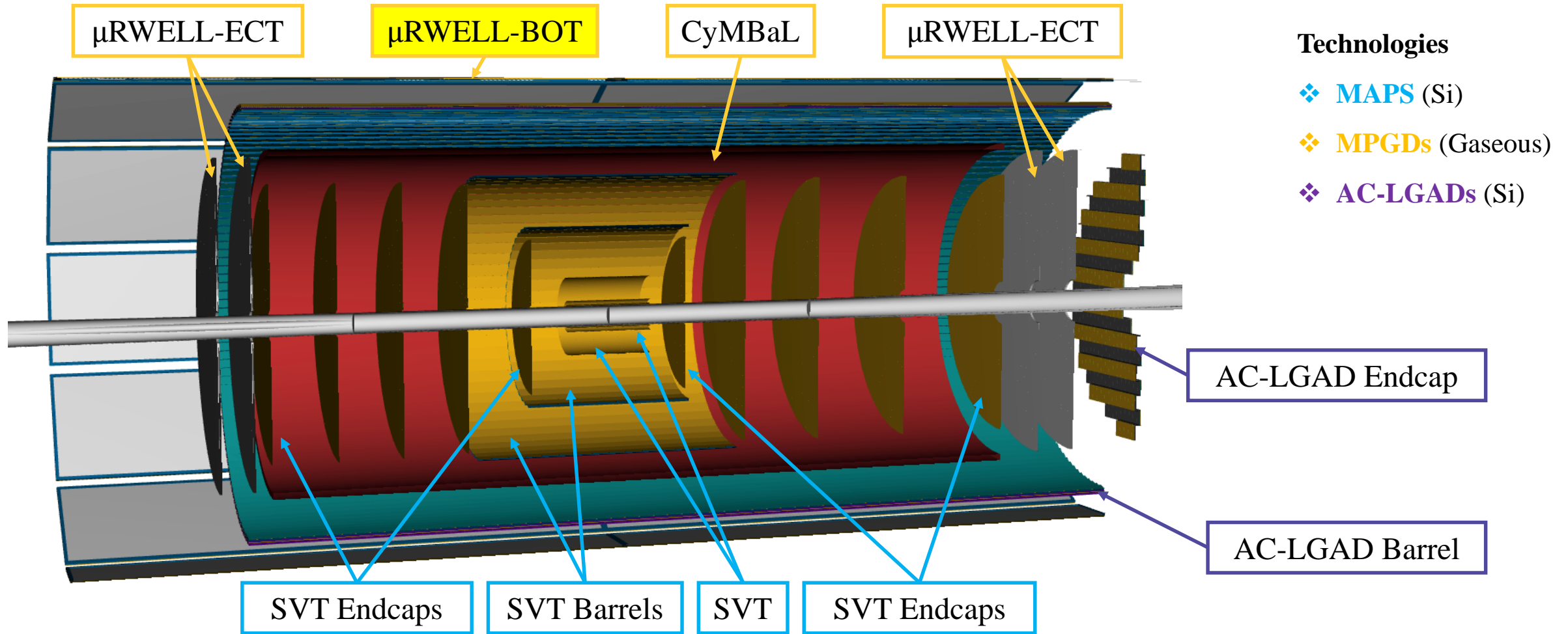
Electron-Ion Collider



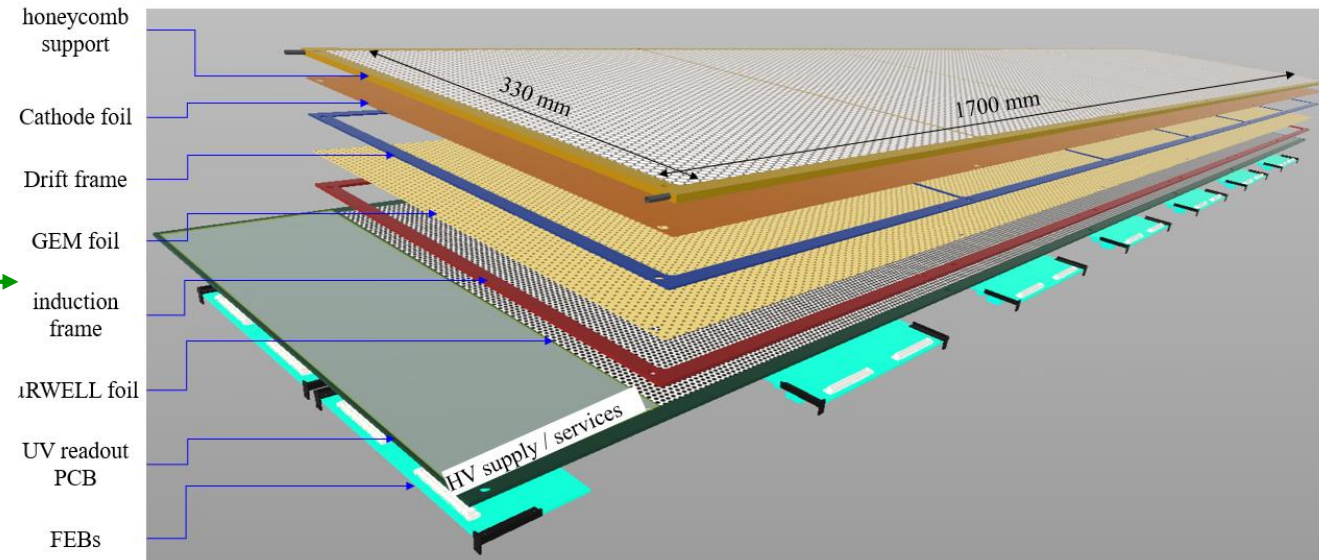
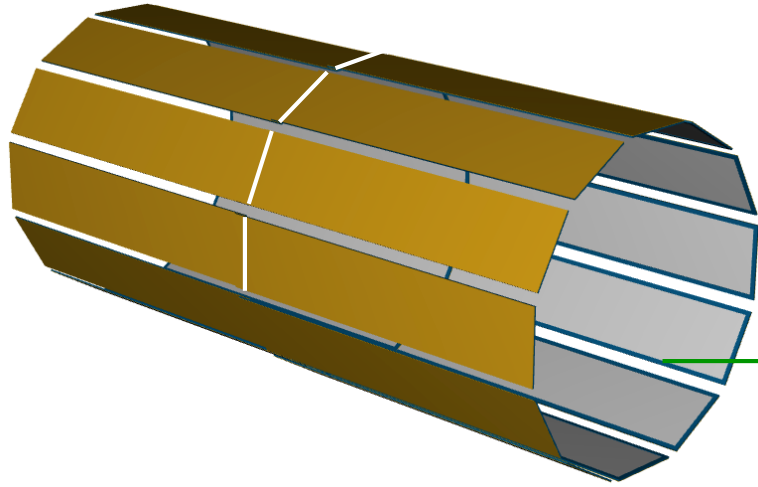
μ RWELL-BOT core team at JLab:

- ❖ **K. Gnanvo** - Project leader for the μ RWELL Barrel Outer Tracker (μ RWELL-BOT)
- ❖ **Seung Joon Lee** - Integration, Electronics ...
- ❖ **Xinzhan Bai** - Module production, Electronics integration ...

Overview of ePIC Tracking Detector



μRWELL-BOT Module:

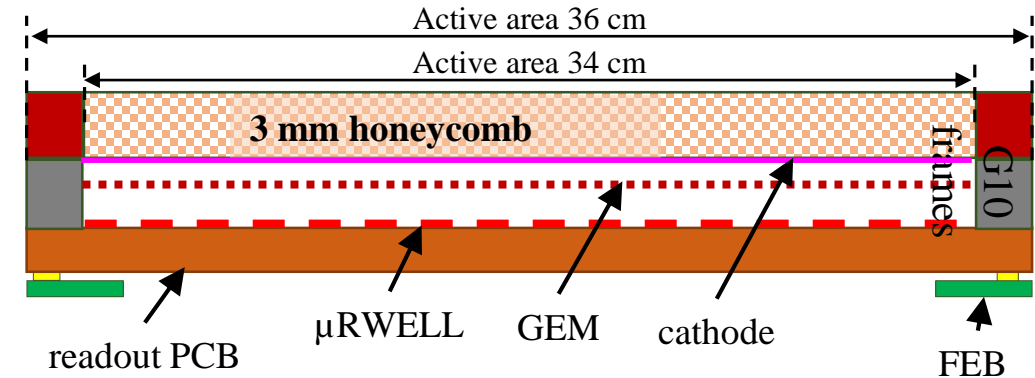


μRWELL-BOT module

- ❖ Thin-gap (1-mm drift) hybrid amplification GEM-μRWELL detector
- ❖ On-detector Front End Boards (FEBS) based on SALSA chips

Requirements:

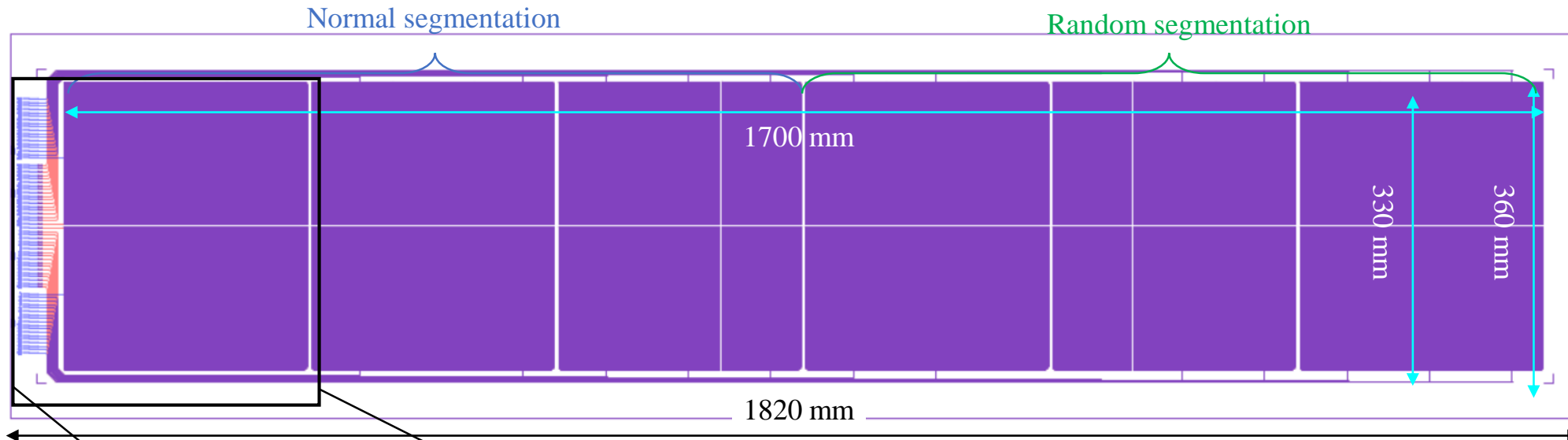
- ❖ Spatial resolution:
 - $R \cdot \phi: < 100 \mu\text{m}$,
 - $z < 100 \mu\text{m}$ (normal tracks), $< 250 \mu\text{m}$ @ 45°
- ❖ Time resolution: 10 ns
- ❖ Efficiency ~97%



cross-section view of thin-gap GEM-μRWELL detector

Electron-Ion Collider

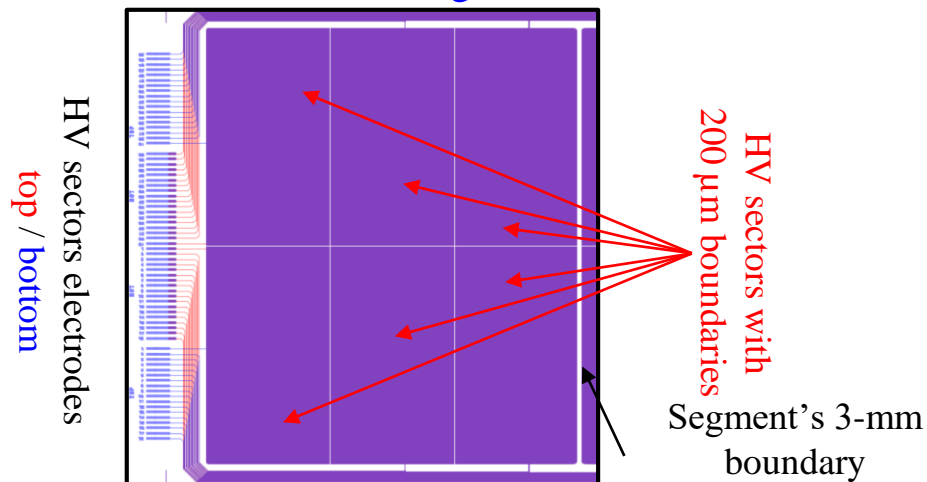
Engineering test article: GEM foil



Foil dimension

- ❖ Total: 1820 mm × 360 mm
- ❖ Active area: 1700 mm × 330 mm

one active segment

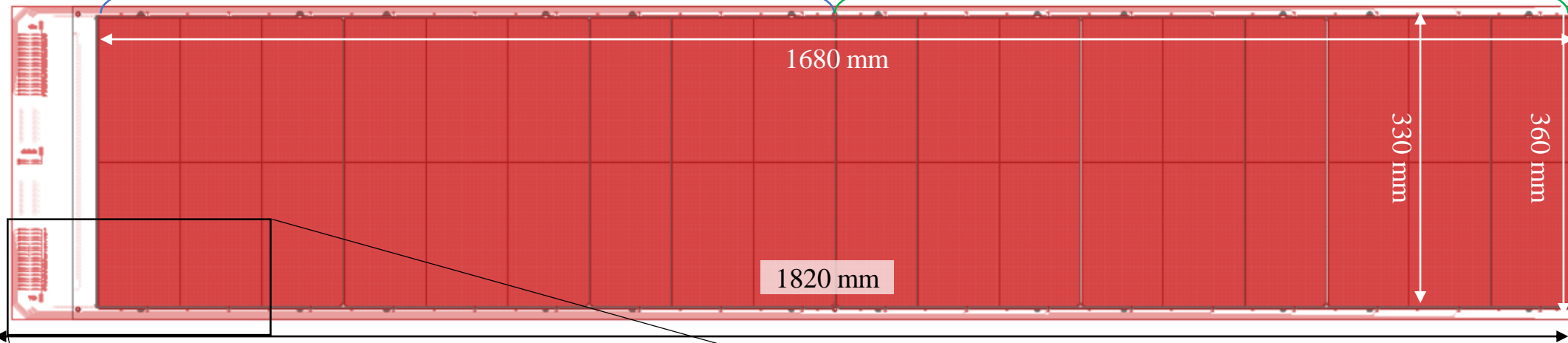


- ❖ Active area divided into 6 active segments of area 330 mm × 283 mm → separated by 3-mm dead area to be glued to the support frames on top & bottom
- ❖ Each segment divided into 6 HV sectors (180 × 96 mm²) → separated by 200 μm dead area
 - 8 sectors on the left side have normal segmentation
 - 8 on the right with random segmentation → Study impact on efficiency
- ❖ Both top and bottom side of the foils are segmented
- ❖ Connection to all 76 HV sectors are on the left side of the foil

Engineering test article: μ RWELL PCB

Normal segmentation

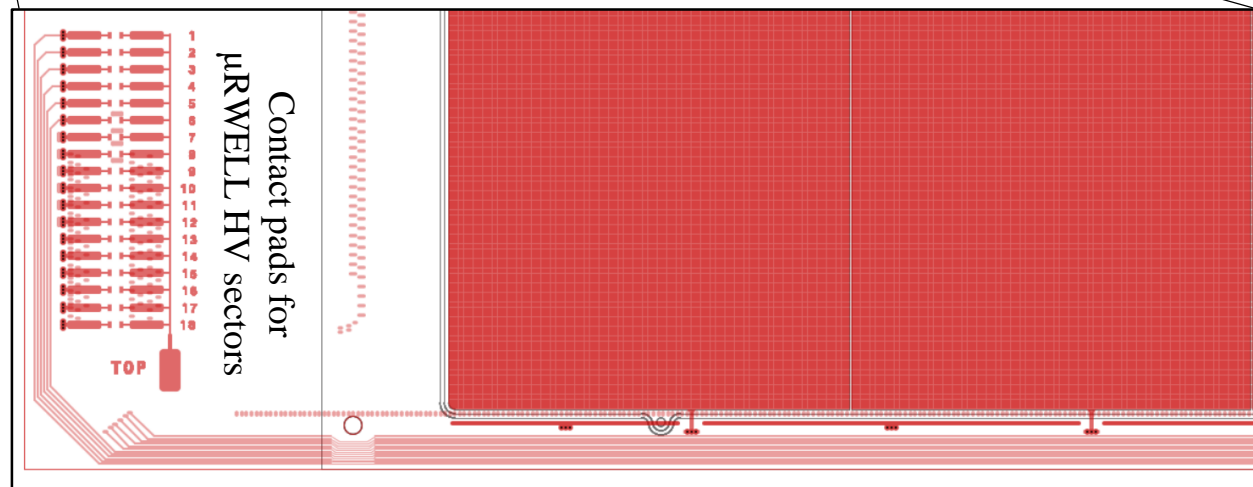
Random segmentation



μ RWELL
dimension

- ❖ Overall:
182 cm \times 36 cm
- ❖ Active area:
168 cm \times 330 cm

Two of the 36 μ RWELL sectors



- ❖ The active area of **36 HV sectors (180 mm \times 96 mm)** similar to the HV sectors separated by 100 μ m dead area
 - The 18 sectors on the left side have **normal segmentation**
 - The 18 on the right have a **random segmentation** \rightarrow Study impact on detector efficiency
- ❖ Connection to all 36 HV sectors on the left side of the foil

Engineering test article: Capacitive-sharing U/V strip readout

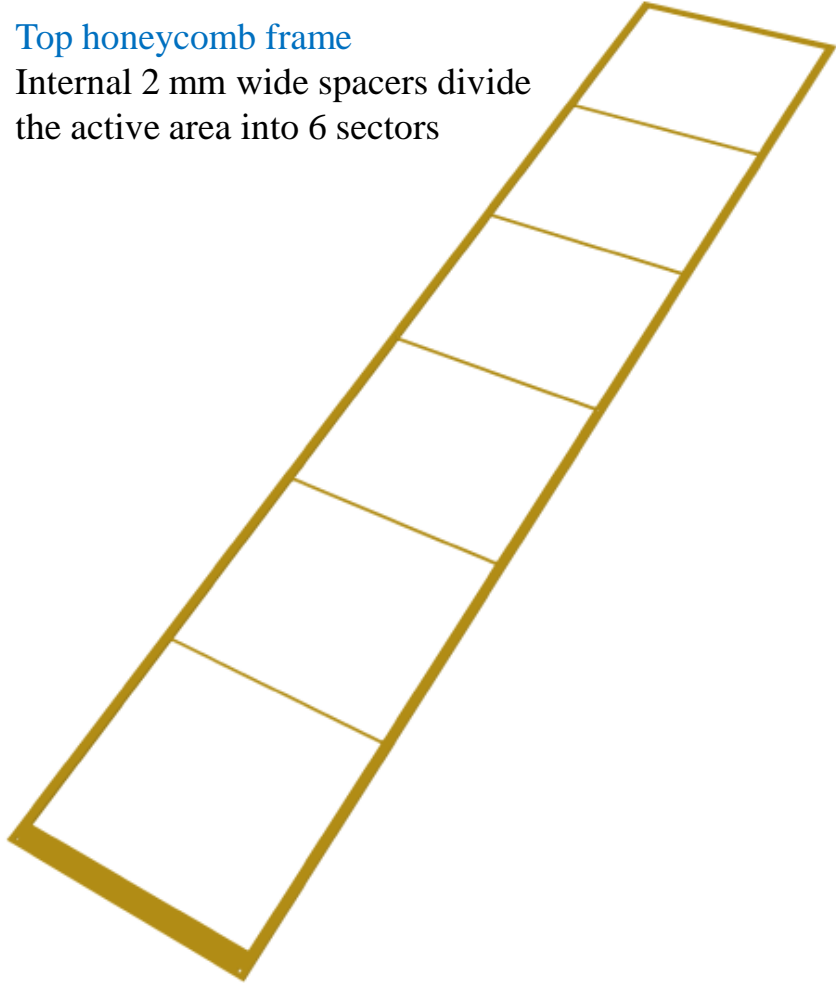


- ❖ 45 degree U / V strips instead of X / Y
- ❖ All connectors at the edge the long side of the detector
- ❖ Pitch = **800 μm** along U / V axis → 1.14 mm along detector edge
- ❖ Strip length = **47 cm** limited strip capacitance concerns
- ❖ Width: top strips (U) = 200 μm and bottom strips (V) = 575 μm
- ❖ 2 layers of capacitive sharing (400 μm and 800 μm) → square pads along U and V axis
- ❖ Total of **3,584 strips** → 28 × 140-pins Hirose connectors with 12 ground pins on the back of the PCB

Engineering test article: Support frames

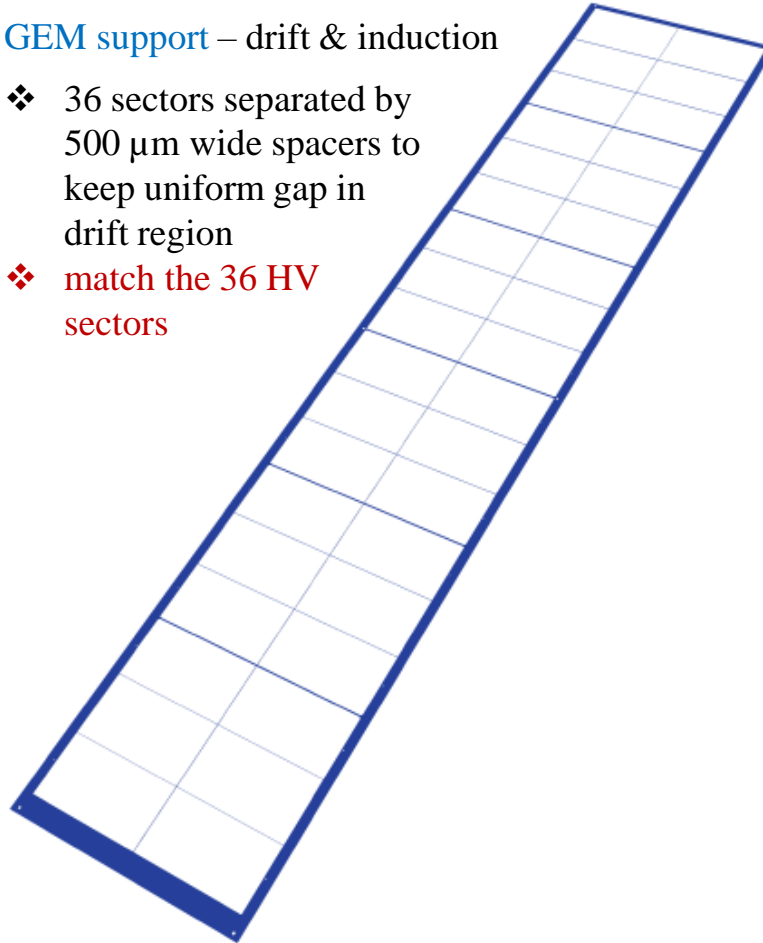
Top honeycomb frame

Internal 2 mm wide spacers divide the active area into 6 sectors



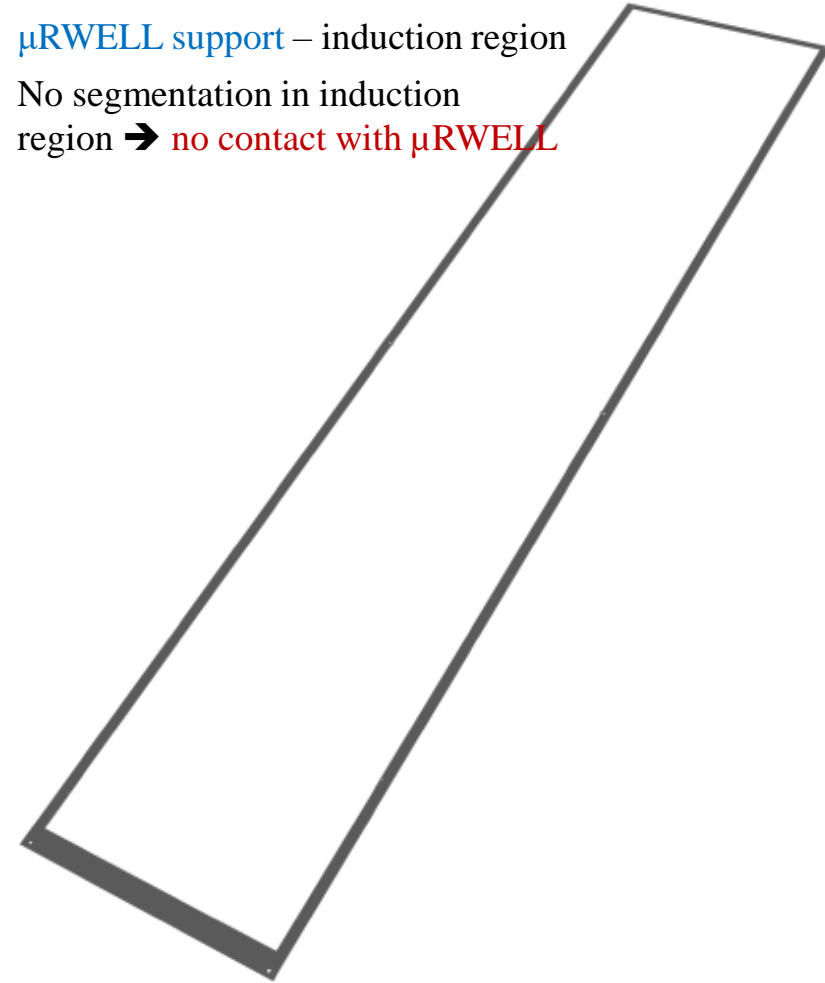
GEM support – drift & induction

- ❖ 36 sectors separated by 500 μm wide spacers to keep uniform gap in drift region
- ❖ match the 36 HV sectors



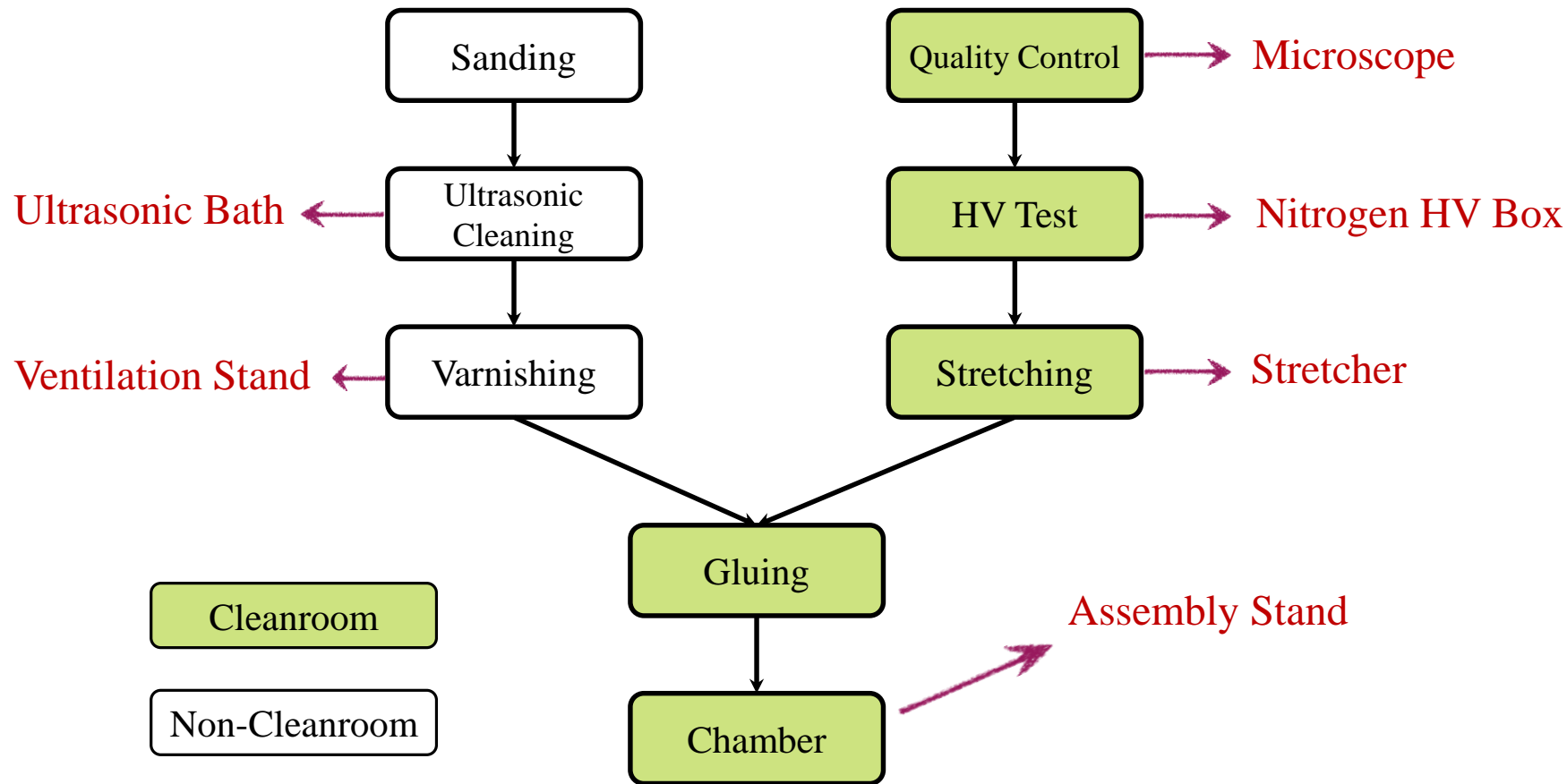
μRWELL support – induction region

No segmentation in induction region \rightarrow no contact with μRWELL



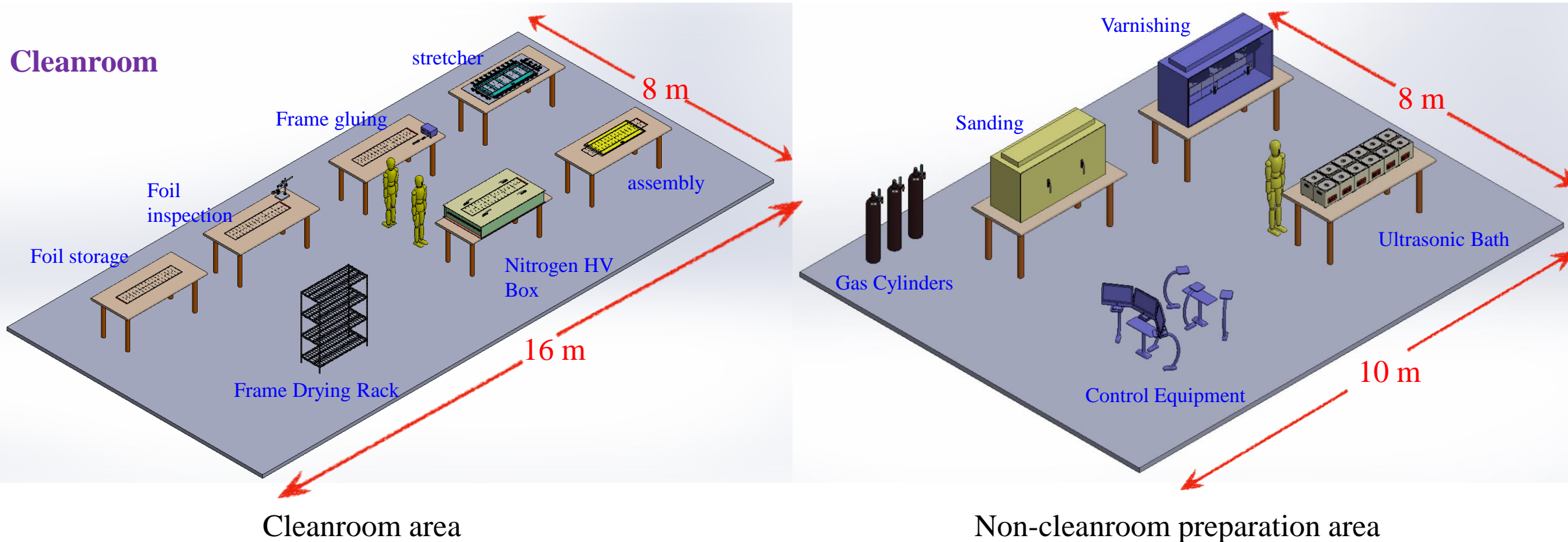
Engineering test article assembly @ JLab: Infrastructure & Equipment needs

Workflow & Equipment



Engineering test article assembly @ JLab: Real estate requirements

- ❖ Cleanroom area: 16 m x 8 m (with all necessary equipment in realistic dimensions)
- ❖ Non-cleanroom preparation area: 10 m x 8 m



Where do we stand with the engineering test article?

- ❖ Fabrication of GEM foil and μ RWELL PCB at the CERN workshop delayed → Estimated delivery is May 2025 (instead of January)
- ❖ Fabrication of all support frames by RESARM (Belgium) is completed → shipment in 2 to 3 weeks after invoice payment
- ❖ We started thinking of the infrastructure, space and equipment needed at JLab for the assembly of the test article
 - ❖ Space for clean room + equipment
 - ❖ Space for detector test + equipment
- ❖ If GEM and μ RWELL are delivered “in time” in May 2025 → assembly will be completed by August / September 2025
 - ❖ In time for test in beam in Fall 2025

Assembly plans: Planning & schedule

06/2025

PED & validation

- Design of full size μ RWELL-BOT completed
- Procurement of GEM foils, μ RWELL PCB – **06/2025**
- Assembly at JLab & test in beam - **12/2025**

12/2026

Pre-production

- Assembly of one pre-production module (**module#0**)
- Setup of infrastructure and equipment in assembly sites

04/2029

Production

- Assembly and QA of 9 production modules at assembly sites
- Full characterization at assembly sites of each module on cosmic stand and with radioactive sources

06/2029

Shipment to JLab

- Shipment of all 24 modules to BNL
- Commissioning at BNL cosmic test stand of all μ RWELL-BOT as well as μ RWELL-ECT

Commissioning & Installation

- Commissioning
- Installation

Backup

JLab RD&I: Large Ultrasonic cleaning bath

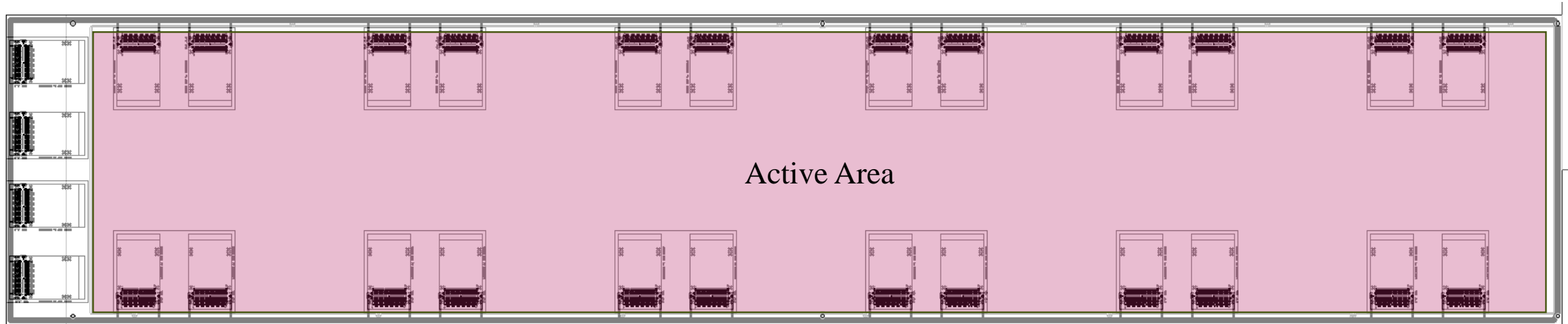


Specifications

Inside Dimensions	70" (L) x 28" (W) x 24" (H)
Overall Dimensions	89" (L) x 33" (W) x 43" (H)
Ultrasonic Power	4000 watts (8000 watts peak)
Ultrasonic Generator	(Four) 40 kHz, 1000 watt
Heat Power	4000 watts
Power Requirement	240 VAC, 50/60 Hz, single phase, 39.2A
Filtration System	7GPM nominal pump with (1) polypro strainer (1) 20 in, polypro filter housing (1) 20-micron, polyspun, filter

Electron-Ion Collider

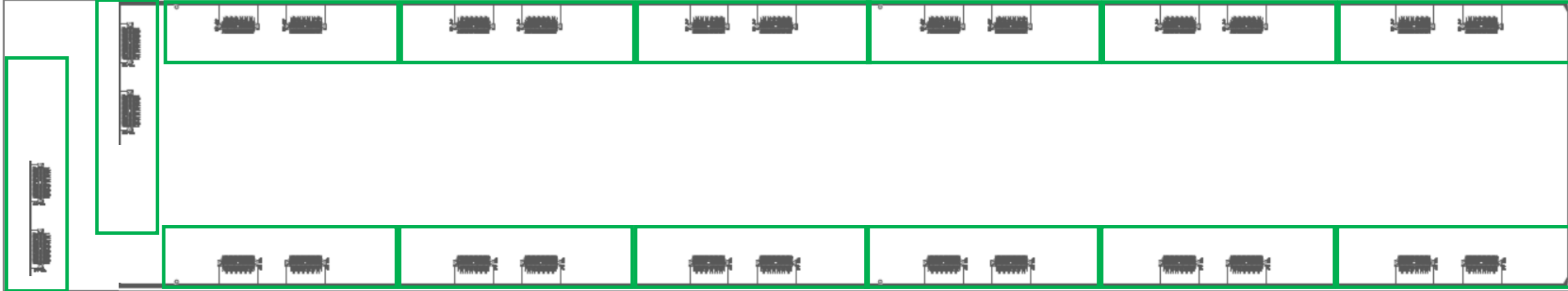
PED Test article: Front End Board (FEB) Layout



- PCB size: 36 cm x 180 cm
- Active Area: 33 cm x 170 cm
- 14 FEBs
- Each FEB has 2 x 144 Hirose FX10 connector (total 256 Channel, 4 x Salsa)
- Each FEB requires 1x DC/DC converter, 1x VTRX board
- Each FEB requires 1x Optical Fiber Connector, 1x Low voltage, and Cooling

Possible FEB arrangement in service area

Option 1: Extend 2 Connectors further → increase the length of the of the PCB by 10 cm



Option 2: Reduce the number of from 4 to 2 Connectors further → increase the strip pitch and remove useless strips

